

PRODUCT TYPE	Quartz Crystal HSX321S			
NOMINAL FREQUENCY	11.059200MHz			
H.ELE. SAMPLE O/N	EOS-J40433-3			
H.ELE. P/N	X3S011059FK1H-V			
RELEASE DATE	2019/05/02			
VERSION	00			
MSL	Level 1			
GREEN PRODUCT	☑ Pb free ☑ RoHS Compliant			
	🗹 HF-Halogen free 🗹 REACH Compliant			
CUSTOMER P/N				
APPLICATION & MODEL				
APPROVED BY CUSTOMER				
	(DATE)			

Harmony Electronics Corp.	
F. S. TSAI (APPROVE)C. C. HOU (CHECK)U. F. CHEN (PREPARE)	Country of Origin: Taiwan Factory Thailand Factory China Factory

HARMONY ELECTRONICS CORPRATION

KAOHSIUNG	ΤΑΙΡΕΙ	THAILAND	Shenzhen	DONGGUAN
TEL: 886-2-265	88883		Email: contactus@h	ele.com.tw



REV. No.	DATE	REASON	REVISE CONTENTS
0	2019/05/02	New	

HARMONY ELECTRONICS CORPRATION

KAOHSIUNG

.

ΤΑΙΡΕΙ

THAILAND SHENZHEN

Email: contactus@hele.com.tw

TEL: 886-2-26588883



Contents

ITEM	PAGE				
1. QUARTZ CRYSTAL UNIT SPECIFICATION	3				
2. DIMENSIONS					
3. MARKING	4				
4. INSIDE STRUCTURE	5				
5. HANDLING SUGGESTIONS	5-6				
6. EMBOSS CARRIER TAPE&REEL	6-7				
7. PACKAGE	7-8				
8. MECHANICAL PERFORMANCE	8-9				
9. ENVIRONMENTAL PERFORMANCE	9				
10. APPENDIX					

HARMONY ELECTRONICS CORPRATION

KAOHSIUNG

THAILAND

AND

SHENZHEN

Email: contactus@hele.com.tw

DONGGUAN

.

ΤΑΙΡΕΙ



1. QUARTZ CRYSTAL UNIT SPECIFICATION

	Ele	ctrical Spe	с.		Nation
Items	Min	Туре	Max	Unit	Notes
1. Frequency (FL)	1	1.059200		MHz	
2. Mode of oscillation:	F	undament	al		
3. Frequency tolerance	-30		+30	ppm	at 25°C±3°C
4. Equivalent resistance (RR)			120	Ω	SERIES
5. Storage temperature range	-40		+125	°C	
6. Operable temperature range	-40		+85	°C	
7. Temperature stability	-30		+30	ppm	-40°C ~ +85°C
8. Loading capacitance (CL)		20.0		рF	
9. Drive level (DL)		10	100	μW	
10. Shunt Capacitance (CO)			2.0	рF	
11. Insulation resistance	500			MΩ	at DC 100V
12. Aging:	-3		+3	ppm/Year	
13. Circuit:	Measured	d in HP/E5:	100A,S&A	250B	

Note: Storage Temperature is only for the product itself.

HARMONY ELECTRONICS CORPRATION

KAOHSIUNG

ΤΑΙΡΕΙ

THAILAND

Dongguan

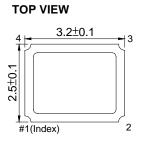
.

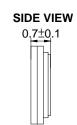
Email: contactus@hele.com.tw

SHENZHEN



2. DIMENSION



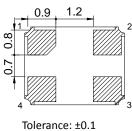


TOP VIEW Internal Connection



Pin	Connections			
#1	Crystal			
#2	GND/Lid			
#3	Crystal			
#4 GND/Lid				
#2,#4	4 GND(connection Co	over)		

BOTTOM VIEW

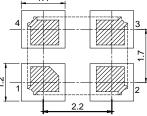


Unit: mm

1.4

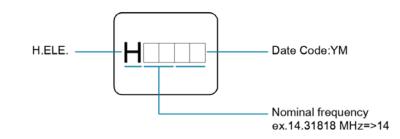
Land Pattern Layout

TOP VIEW



* Note: The Index mark was defined by the BASE suppliers.

3. MARKING



Note:

1. Laser marking.

2. Date Code:

	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019
Y=Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	0	1	2	3	4	5	6	7	8	9

M=Month	Jan.	Feb.	Mar.	Apr.	May.	Jun.	Jul.	Aug.	Sep.	Oct.	Nov.	Dec.
Code	А	В	С	D	E	F	G	Н	J	К	L	М

HARMONY ELECTRONICS CORPRATION

KAOHSIUNG

ΤΑΙΡΕΙ

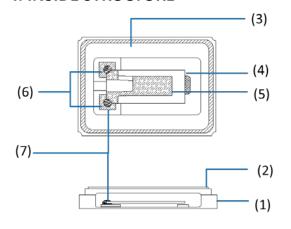
THAILAND

Dongguan

SHENZHEN

Email: contactus@hele.com.tw





Ref	Reference drawing							
	No.	Component	Material	Note				
	(1)	Base	Ceramic	Al ₂ O ₃				
	(2)	Lid	Metal	Fe- Ni –Co Ni Plating				
	(3)	Kovar	Metal	Fe- Ni -Co				
	(4)	Crystal Blank	Quartz	SiO ₂ Rectangular At-Cut				
	(5)	Electrode	Metal	-				
	(6)	PAD	Metal	W Ni Plating Au Plating				
	(7)	Connective Adhesive	Silver Powder	Ag				

%The use prohibition chemistry substance of Table 1 of DHE-0204-1 (HE-QA-24) is not included in this item.

5. HANDLING SUGGESTION

Reflow Condition

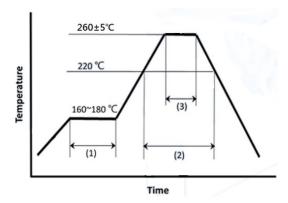
Please stay with our proposed reflow condition and do soldering within 2 times.

		0	
(1)	Preheat	160~180deg.C	120 sec.
(2)	Primary heat	>=220 deg.C	100±20 sec.

(3) Peak 260±5 deg.C 10 sec. Max.

Manual Solder iron (Example)

Bit temp.: 350°C max., Time: 3sec max., Each terminal only should be soldered once.



Mounting Conditions

Our products are suitable for most automated SMT processes. However, we strongly advise all our customers to conduct SMT sampling prior to mass production in order to make sure production processes will not affect the properties and specifications of our product. Seal welding and mounting procedures involving the use of ultra-sonic processes are not recommended and will affect and/or damage the internal properties of our product. Excessive shock during the mounting process will also affect the product and we strongly recommend setting SMT conditions to minimize such conditions.

If a possibility of the PCB being warped exists we strongly advise to ensure the degree of warping will not affect the product.

Please also ensure the operating characteristics and or soldering conditions are all within the specifications of use for our product.

Ultimately the worst case scenario of all the above will lead to cases of non-oscillation but other negative effects are also likely should our products be used in an inappropriate way. Please note such cases of misuse and its related quality issues are not included in our product warranty.

HARMONY ELECTRONICS CORPRATION

Kaohsiung

ΤΑΙΡΕΙ

THAILAND

Email: contactus@hele.com.tw

DONGGUAN

SHENZHEN



Cleansing Conditions

General cleaning solutions may be used to clean our products but we always recommend testing to be performed prior to mass production processes. Ultrasonic cleaning procedures are not recommended and we strongly advise other forms of cleansing to be evaluated first. Unsuitable cleansing may lead to a number of negative effects such as damage to the product surface, discoloration of the product, corrosion of the package, package contamination, illegible marking, etc. Please note cases of unadvised treatment and its related quality issues are not included in our product warranty.

Storage Conditions

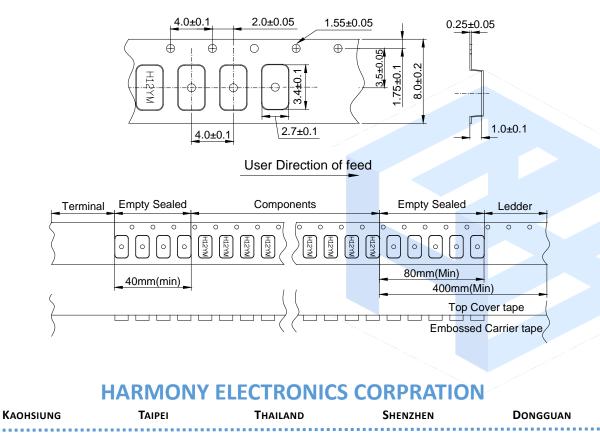
Please ensure our products are preserved appropriately in their original packaging. Irregular environmental instances of moisture will affect our product's stability and may cause problems such as frequency instability, soldering ability and conditions, package defects, and other problems. It is essential to keep our products in a clean dust-free environment out of direct sunlight.

Our products' storage conditions should at least meet the following condition: Environmental Temperature: + 40 degrees Celsius Maximum Relative Humidity: 80% Maximum

Please note storage instances which do not conform to our guidelines and the related quality issues produced as an outcome are not included in our product warranty.

6. EMBOSS CARRIER TAPE AND REEL

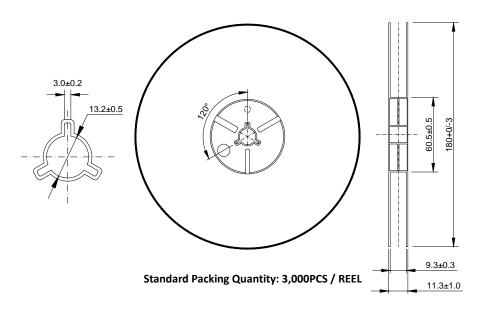
Carrier Tape



Email: contactus@hele.com.tw



Reel



Material of The Tape

Таре	Material
Carrier tape	PS Conductive
Top tape	PET

Joint of tape

The carrier-tape and top cover-tape should not be jointed.

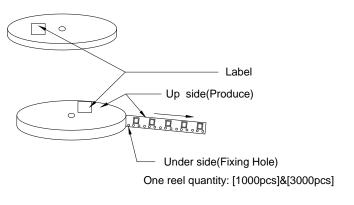
Release strength of cover tape

The force should be controlled between 0.1N to 0.7N under following condition. Pulling direction: 165° to 180° Speed: 300mm/min. Otherwise unless specified.



Other standards shall be based on JIS C 0806-1990.

7. PACKAGE



Label Contents		
TYPE: SPEC. No.:		PASS H10
Parts No.: Lot No.:		
FREQ.:	MHz	HSF
Q'TY: HARMONY ELECTRONICS	PCS CORP.	
The label will be stic	kled on all re	els.

HARMONY ELECTRONICS CORPRATION

KAOHSIUNG

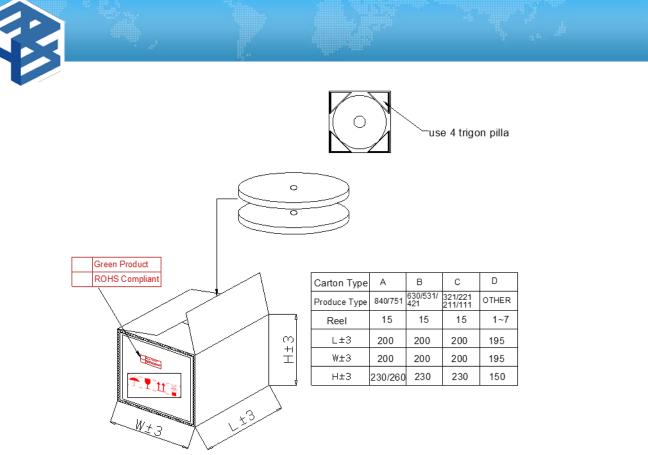
ΤΑΙΡΕΙ

THAILAND

DONGGUAN

TEL: 886-2-26588883

SHENZHEN DOI Email: contactus@hele.com.tw



(1)Top and bottom with 2.3cm thickness

- foam-rubber cushion for protection.
- 2 Carton's Q'TY:1~15 pcs.
- ③Carton Type=A,B,C use 4 trigon pillar to fasten the Reel.
- (4)Need to add 3 pages dry agent in each outer box.

8. MECHANICAL PERFORMANCE

	ltem	Test M	ethods	Specifications Code
1	Shock	Dropping from 120 cm height 3 times on 30 mm Concrete floor. Refer to: JIS C 60068-2-32		Α
2	Vibration	Frequency 10-55Hz, Sine Wave full amplitude of 0.8mm to X, Y and Z 3 axes, 2 cycles and duration of 2 hours to each direction. Refer to: JIS C 60068-2-6/ MIL-HDBK-781A 6.5.2		A
3	Leakage Test	Leak Rate 1.0x10 ⁻⁹ Pa-m ³ /sec. Max. Measured by Helium leak detector. Refer to: JIS C 60068-2-17		
4	Solder ability	After applying ROSIN Flux, dipping in solder bath at 245deg.C ±5deg.C for 3 ±0.5 sec. Refer to: JIS C 60068-2-20/ JIS C 60068-2-58		В
5	Bending Strength	Mount a sample on board. Apply Pressure to the center of board until it is bent to 3 mm and hold for 5 ±1 sec. Pressure speed: 0.5 mm/sec. Refer to: EIAJ ET-7403/ JIS C 60068-2-21	Pressure rod 20 R230 Board 45 ± 2 45 ± 2	A

HARMONY ELECTRONICS CORPRATION

KAOHSIUNG

ΤΑΙΡΕΙ

THAILAND

SHENZHEN

Email: contactus@hele.com.tw



6	Adhesion	Mount a sample on the circuit board. Apply pressure vertically to the side of specimen attached to the circuit board with the pressure jig. Pressure: 5N for 10±1 sec. Refer to: EIAJ ET-7403 JIS C 60068-2-21	Scratch tool	А
7	Body strength	Apply pressure to the center of body with the R0.5 pressure jig. pressure :10N for 10±1sec Refer to: EIAJ ET-7403 JIS C 60068-2-21	Pressure ad $P_{\text{ressure}} \downarrow \qquad R0.5$ $W = \frac{1}{2}$ $L = \frac{1}{2}$ $L = \frac{1}{2}$	Α

9. ENVIRONMENT PERFORMANCE

	ltem	Test Methods	Specifications Code
1	Resistance of Soldering Heat	Performing as the following reflow: Refer to: JIS C 60068-2-58	А
2	Humidity	Temperature 60°C±2°C, RH 90~95%, duration of 240 hours. Back to room temperature first, then check the component after 1~2 hours. Refer to: JIS C 60068-2-3	
3	Storage in Low Temperature	-40deg.C ±2deg.C, duration of 240 hours. Back to the room temperature first, then check the component after 1~2 hours. Refer to: JIS C 60068-2-1	А
4	Storage in High Temperature	+85deg.C ±2deg.C, duration of 240 hours. Back to the room temperature first, then check the component after 1~2 hours. Refer to: JIS C 60068-2-2	A
5	Thermal shock	-55deg.C ±2deg.C (30min) ↔ +125deg.C ±2deg.C (30min) 25 cycles. And Temperature Increasing/reducing time ≦ 3mins. Back to the room temperature first, then check the component after 1~2 hours. Refer to: JIS C 0025	A

Specifications code	Specifications	
Α	FREQ. DRIFT: ±5 ppm Max, RESISTANCE DRIFT: ±15% or 2Ω	
В	More than 90% of lead shall be covered by new solder.	

HARMONY ELECTRONICS CORPRATION

Kaohsiung

THAILAND

SHENZHEN

Email: contactus@hele.com.tw

ΤΑΙΡΕΙ

FACTORY LOCATION

HEAD OFFICE/TAIWAN FACTORY

NO.39, HUADONG RD., DALIAO DIST., DAFA INDUSTRIAL PARK, KAOHSIUNG CITY 831.

CHINA FACTORY

SHEN ZHEN JU YUAN INDUSTRIAL PARK, QIAO TANG ROAD, TANG WEI COMMUNITY, FUYONG, BAOAN DISTRICT, SHEN ZHEN CITY (Post Code:518103).

DONGGUAN BUILDING A1, HUAZHI INDUSTRIAL PARK, NO.38, JINGFU EAST ROAD, DALANG TOWN, DONGGUAN CITY.

THAILAND FACTORY

66MOO 5, KAONGU-BEOKPRAI RD., T.BEOKPRAI, A. BANPONG, RATCHABURI PROVINCE 70110.

SERVICE CENTER

TAIPEI OFFICE

2F., NO.409, SEC.2, TIDING BLVD., NEIHU DISTRICT, TAIPEI CITY 114, TAIWAN. TEL: 886-2-26588883 FAX: 886-2-26588683

CONTACT INFORMATION

E-MAIL: contactus@hele.com.tw



X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Crystals category:

Click to view products by Harmony manufacturer:

Other Similar products are found below :

CS325S2400000ABJT 718-13.2-1 MC405 32.0000K-R3:PURE SN FC-135R 32.7680KF-A3 7A-40.000MAAE-T 7B-27.000MBBK-T FL2000085 9B-15.360MBBK-B 9C-7.680MBBK-T ASH7K-32.768KHZ AT-41.600MAGQ-T BTD1062E05A-513 LFXTAL066198Cutt 9C-14.31818MBBK-T FA-238 50.0000MB30X-K3 FC-12M 32.7680KA-AC3 SSPT7F-9PF20-R FX325BS-38.88EEM1201 LFXTAL065253Cutt LFXTAL066431Cutt XT9S20ANA14M7456 XT9SNLANA16M 646G-24-2 7A-24.576MBBK-T 7B-30.000MBBK-T WX26-32.768K-6PF 9B-14.31818MBBK-B CD1AM 7B-25.000MAAE-T 7A-14.31818MBBK-T 6504-202-1501 6526-202-1501 FA-118T 27.1200MB50P-K0 FC-135R 32.7680KA-A3 ABM12-104-37.400MHZT ABLS-10.000MHZ-D3W-T BTJ112E01E-513 BTJ722K01C-7067 BTL-20-513 TSX-3225 24.0000MF15X-AC TSX-3225 16.0000MF18X-AC BTJ120E02C BTL-12-513 7A-10.000MBBK-T 7A-11.0592MBBK-T ABM12-103-24.000MHZT CS325S2500000ABJT ABM3B-25.000MHZ-B2-X-T FC-135 32.7680KA-A5 FX0800015